



#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
	45mΩ @ V <sub>GS</sub> = 4.5V	4.9 A
20V	65mΩ @ V <sub>GS</sub> = 2.5V	4.1 A

#### **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- LED Lighting
- Charging applications in portable equipment
- **DC-DC Converters**
- Motor Control



Top View

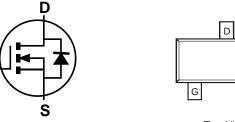


#### **Features and Benefits**

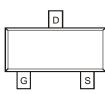
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

#### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish —Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 3
- Terminals Connections: See Diagram Below
- Weight: 0.009 grams (Approximate)



**Internal Schematic** 



Top View

### Ordering Information (Note 5)

Part Number	Case	Packaging
ZXMN2F30FHQTA	SOT23	3,000/Tape & Reel

G

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

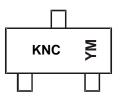
2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/quality/product\_compliance\_definitions/.

5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

# **Marking Information**



KNC = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$ = Year (ex: D = 2016) M = Month (ex: 9 = September)

Date Code Kev

Date Code Key												
Year	2016		2017	2018		2019	2020		2021	2022		2023
Code	D		E	F		G	Н			J		K
Month	Jan	Feb	Mar	Apr	Мау	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Units
Drain-Source Voltage		V <sub>DSS</sub>	20	V
Gate-Source Voltage		V <sub>GSS</sub>	±12	V
Continuous Drain Current (Note 7) $V_{GS} = 4.5V$ Steady State $T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$		ID	4.9 4.0	А
Maximum Continuous Body Diode Forward Curre	ent (Note 7)	Is	1.6	A
Pulsed Drain Current (10µs pulse, duty cycle = 1	%)	IDM	22.6	A

# **Thermal Characteristics**

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 6)		PD	0.96	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R <sub>0JA</sub>	131	°C/W
Total Power Dissipation (Note 7)		PD	1.4	W
Thermal Resistance, Junction to Ambient (Note 7)	Steady State	R <sub>θJA</sub>	89	°C/W
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	Gymbol	WIIII	тур	Max	Onic	rest condition
Drain-Source Breakdown Voltage	<b>BV</b> <sub>DSS</sub>	20	-	-	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current $T_J = +25^{\circ}C$	I <sub>DSS</sub>	-	-	1	μA	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	I <sub>GSS</sub>	-	-	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						· · · ·
Gate Threshold Voltage	V <sub>GS(TH)</sub>	0.6	0.9	1.5	V	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$
Static Drain-Source On-Resistance		-	-	45	mΩ	$V_{GS} = 4.5V, I_D = 2.5A$
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	-	-	65	11122	$V_{GS} = 2.5V, I_D = 2.0A$
Diode Forward Voltage	V <sub>SD</sub>	-	0.75	1.2	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.25A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	I	452	-	pF	
Output Capacitance	Coss	-	102	-	pF	−V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V −f = 1.0MHz
Reverse Transfer Capacitance	C <sub>rss</sub>	I	58	-	pF	
Total Gate Charge	Qg	-	4.8	-	nC	
Gate-Source Charge	Q <sub>gs</sub>	-	1	-	nC	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 3.5A$
Gate-Drain Charge	Q <sub>gd</sub>	-	1.2	-	nC	
Turn-On Delay Time	t <sub>D(ON)</sub>	-	2.9	-	ns	
Turn-On Rise Time	t <sub>R</sub>	-	5.6	-	ns	$V_{DS} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	t <sub>D(OFF)</sub>	-	19.4	-	ns	$R_G = 6\Omega, I_D = 1A$
Turn-Off Fall Time	tF	-	10.2	-	ns	7

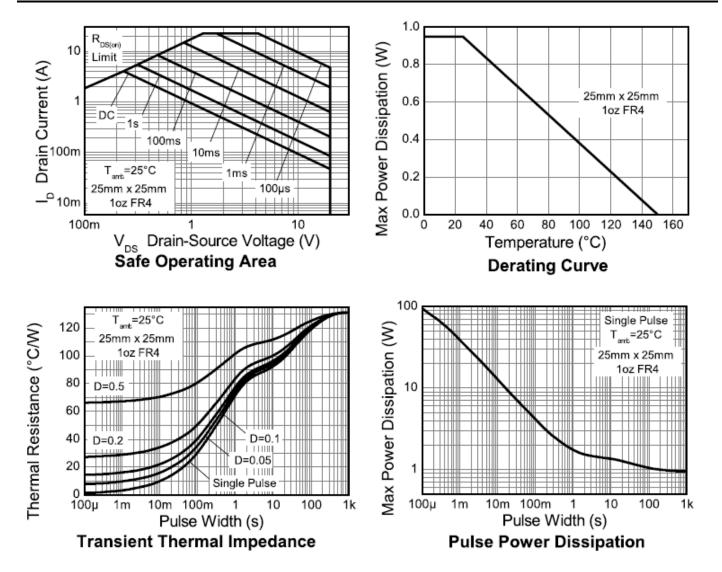
Notes:

Device mounted on FR-4 PCB, with minimum recommended pad layout.
Device mounted on 1" x 1" FR-4 PCB with high coverage 2oz. Copper, single sided.
Short duration pulse test used to minimize self-heating effect.

9. Guaranteed by design. Not subject to product testing.

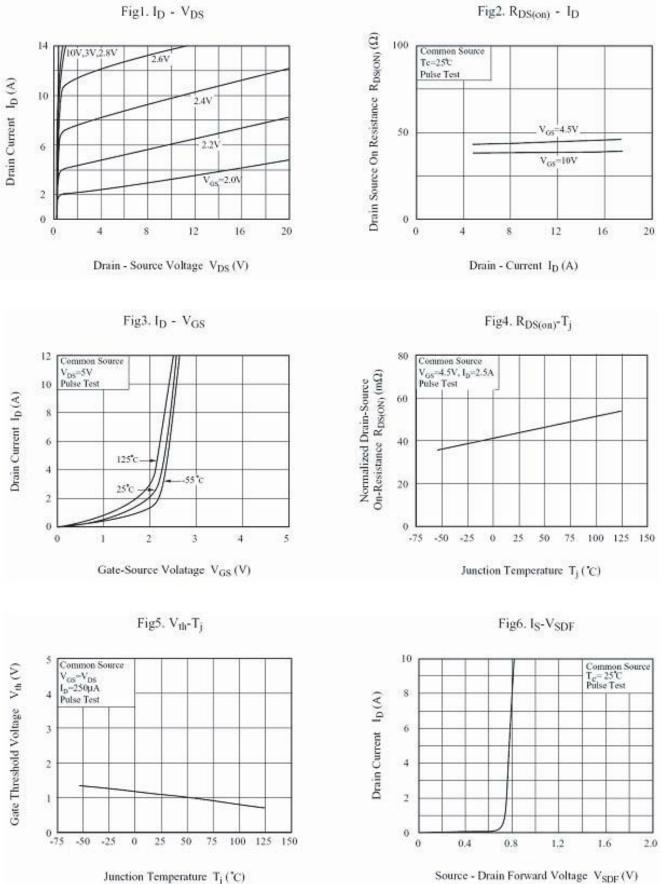


### Thermal characteristics





# **Typical Characteristics**

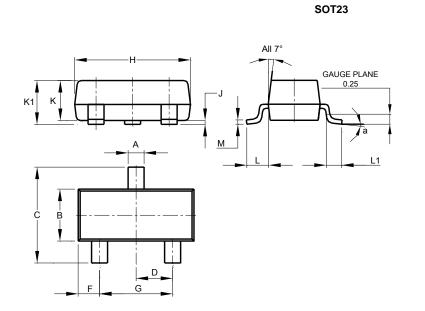


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# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

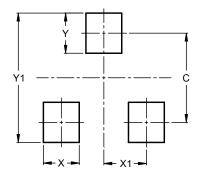


SOT23							
Dim	Min	Тур					
Α	0.37	0.51	0.40				
в	1.20	1.40	1.30				
C	2.30	2.50	2.40				
D	0.89	1.03	0.915				
F	0.45	0.60	0.535				
G	1.78	2.05	1.83				
Н	2.80	3.00	2.90				
J	0.013	0.10	0.05				
κ	0.890	1.00	0.975				
K1	0.903	1.10	1.025				
L	0.45	0.61	0.55				
L1	0.25	0.55	0.40				
Μ	0.085	0.150	0.110				
а	0°	8°					
All Dimensions in mm							

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



Dimensions	Value (in mm)
С	2.0
Х	0.8
X1	1.35
Y	0.9
Y1	2.9



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